

SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE**Publication number:** JP3102843 (A)**Publication date:** 1991-04-30**Inventor(s):** KAWANOBE TORU**Applicant(s):** HITACHI LTD; HITACHI TOKYO ELECTRONICS**Classification:**

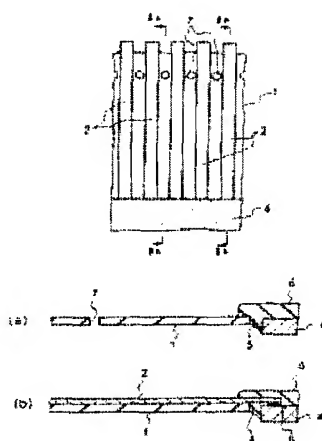
- International: H01L21/60; H01L21/02; (IPC1-7): H01L21/60

- European:

Application number: JP19890240027 19890918**Priority number(s):** JP19890240027 19890918**Abstract of JP 3102843 (A)**

PURPOSE: To enable a film to be bent easily and prevent burn-out of a lead wire effectively by providing a plurality of openings along a specified direction at a region where no lead wire of the film is formed.

CONSTITUTION: A lead wire 2 is formed on one surface of a film 1, a semiconductor chip 4 is connected to one edge of this lead wire, and a plurality of openings 7 are provided along a specified direction at a region where no lead wire 2 of the film 1 is formed. The opening 7 can be formed by irradiating laser beam onto the film 1 or by the etching method, a long groove for making thin the film thickness along a specified direction is provided on the rear surface side of the film 1, or a long groove may be formed by masking one part of the film 1 when cladding an insulation film on the surface of the film 1.



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